

TinyLogic ULP-A Dual Inverter

NC7WV04

The NC7WV04 is a dual inverter in tiny footprint packages. The device is designed to operate for $V_{CC} = 0.9 \text{ V}$ to 3.6 V.

Features

- Designed for 0.9 V to 3.6 V V_{CC} Operation
- 1.6 ns t_{PD} at 3.3 V (Typ)
- Inputs/Outputs Over-Voltage Tolerant up to 3.6 V
- I_{OFF} Supports Partial Power Down Protection
- Source/Sink 24 mA at 3.3 V
- Available in SC−88A and MicroPak[™] Packages
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

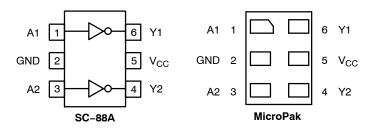


Figure 1. Pinout Diagrams (Top Views)

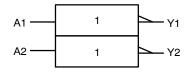


Figure 2. Logic Symbol

MARKING DIAGRAMS



SIP6 1.45X1.0 MicroPak CASE 127EB



CC = Specific Device Code

KK = 2-Digit Lot Run Traceability Code

XY = 2-Digit Date CodeZ = Assembly Plant Code



XXX = Specific Devic Code

M = Date Code*

Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation and/or position may vary depending upon manufacturing location.

ORDERING INFORMATION

See detailed ordering, marking and shipping information on page 6 of this data sheet.

PIN ASSIGNMENT

Pin	Function
1	A1
2	GND
3	A2
4	Y2
5	V _{CC}
6	Y1

FUNCTION TABLE

A Input	Y Output
L	Н
Н	L

MAXIMUM RATINGS

Symbol	Characteristics	Value	Unit	
V _{CC}	DC Supply Voltage		-0.5 to +4.3	V
V _{IN}	DC Input Voltage		-0.5 to +4.3	V
V _{OUT}		-Mode (High or Low State) Tri-State Mode (Note 1) r-Down Mode (V _{CC} = 0 V)	-0.5 to V _{CC} + 0.5 -0.5 to +4.3 -0.5 to +4.3	V
I _{IK}	DC Input Diode Current	V _{IN} < GND	-50	mA
I _{OK}	DC Output Diode Current	V _{OUT} < GND	-50	mA
l _{OUT}	DC Output Source/Sink Current		±50	mA
I _{CC} or I _{GND}	DC Supply Current per Supply Pin or Ground Pin		±50	mA
T _{STG}	Storage Temperature Range		-65 to +150	°C
TL	Lead Temperature, 1 mm from Case for 10 Seconds		260	°C
TJ	Junction Temperature Under Bias		+150	°C
θЈА	Thermal Resistance (Note 2)	SC-88A MicroPak	377 154	°C/W
P _D	Power Dissipation in Still Air	SC-88A MicroPak	332 812	mW
MSL	Moisture Sensitivity		Level 1	-
F _R	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	-
V _{ESD}	ESD Withstand Voltage (Note 3)	Human Body Model Charged Device Model	2000 1000	V
I _{Latchup}	Latchup Performance (Note 4)		±100	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Applicable to devices with outputs that may be tri-stated.

2. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2 ounce copper trace no air flow per JESD51-7.

3. HBM tested to EIA / JESD22-A114-A. CDM tested to JESD22-C101-A. JEDEC recommends that ESD qualification to EIA/JESD22-A115A (Machine Model) be discontinued.

4. Tested to EIA/JESD78 Class II.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter			Max	Unit
V _{CC}	Positive DC Supply Voltage		0.9	3.6	V
V _{IN}	DC Input Voltage	0	3.6	V	
V _{OUT}	DC Output Voltage	Active–Mode (High or Low State) Tri–State Mode (Note 1) Power–Down Mode (V_{CC} = 0 V)	0 0 0	V _{CC} 3.6 3.6	
T _A	Operating Temperature Range		-40	+85	°C
t _r , t _f	Input Transition Rise and Fall Time	V_{CC} = 3.3 V \pm 0.3 V	0	10	ns/V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

DC ELECTRICAL CHARACTERISTICS

				Т	$T_A = 25^{\circ}C$		$T_A = -40^{\circ}$	C to +85°C	
Symbol	Parameter	Condition	V _{CC} (V)	Min	Тур	Max	Min	Max	Unit
V _{IH}	High-Level Input		0.9	-	0.5	-	-	-	V
	Voltage		1.1 to 1.3	0.65 x V _{CC}	-	-	0.65 x V _{CC}	-	
			1.4 to 1.6	0.65 x V _{CC}	-	-	0.65 x V _{CC}	-	
			1.65 to 1.95	0.65 x V _{CC}	-	-	0.65 x V _{CC}	-	
			2.3 to <2.7	1.6	-	-	1.6	-	
			2.7 to 3.6	2.0	-	-	2.0	-	
V _{IL}	Low-Level Input		0.9	-	0.5	-	-	-	V
	Voltage		1.1 to 1.3	-	-	0.35 x V _{CC}	-	0.35 x V _{CC}	
			1.4 to 1.6	-	-	0.35 x V _{CC}	-	0.35 x V _{CC}	
			1.65 to 1.95	-	-	0.35 x V _{CC}	-	0.35 x V _{CC}	
			2.3 to <2.7	_	-	0.7	_	0.7	
			2.7 to 3.6	-	-	0.8	-	0.8	
V _{OH}	High-Level Output	$V_{IN} = V_{IH}$ or V_{IL}							V
	Voltage	I _{OH} = -100 μA	0.9	_	V _{CC} – 0.1	_	-	-	
			1.1 to 1.3	V _{CC} - 0.1	-	-	V _{CC} - 0.1	-	
			1.4 to 1.6	V _{CC} - 0.1	-	-	V _{CC} - 0.1	-	
			1.65 to 1.95	V _{CC} - 0.2	-	-	V _{CC} - 0.2	-	
			2.3 to <2.7	V _{CC} - 0.2	-	-	V _{CC} - 0.2	-	
			2.7 to 3.6	V _{CC} - 0.2	_	-	V _{CC} - 0.2	-	
		$I_{OH} = -2 \text{ mA}$	1.1 o 1.3	0.75 x V _{CC}	-	-	0.75 x V _{CC}	-	
		$I_{OH} = -4 \text{ mA}$	1.4 to 1.6	0.75 x V _{CC}	_	-	0.75 x V _{CC}	-	
		$I_{OH} = -6 \text{ mA}$	1.65 to 1.95	1.25	-	-	1.25	-	
			2.3 to <2.7	2.0	_	-	2.0	-	
		I _{OH} = -12 mA	2.3 to <2.7	1.8	-	-	1.8	-	
			2.7 to 3.6	2.2	-	-	2.2	-	
		I _{OH} = -18 mA	2.3 to <2.7	1.7	_	-	1.7	-	
			2.7 to 3.6	2.4	-	-	2.4	-	
		$I_{OH} = -24 \text{ mA}$	2.7 to 3.6	2.2	_	-	2.2	_	

DC ELECTRICAL CHARACTERISTICS (continued)

					T _A = 25°C			°C to +85°C	
Symbol	Parameter	Condition	V _{CC} (V)	Min	Тур	Max	Min	Max	Unit
V _{OL}	Low-Level	$V_{IN} = V_{IH}$ or V_{IL}							V
	Output Voltage	I _{OL} = 100 μA	0.9	-	0.1	-	_	-	
			1.1 to 1.3	-	-	0.1	-	0.1	
			1.4 to 1.6	-	-	0.1	-	0.1	
			1.65 to 1.95	-	-	0.2	-	0.2	
			2.3 to < 2.7	-	-	0.2	-	0.2	
			2.7 to 3.6	-	-	0.2	-	0.2	
		I _{OL} = 2 mA	1.1 o 1.3	-	_	0.25 x V _{CC}	-	0.25 x V _{CC}	
		I _{OL} = 4 mA	1.4 to 1.6	-	-	0.25 x V _{CC}	-	0.25 x V _{CC}	
		I _{OL} = 6 mA	1.65 to 1.95	-	_	0.3	-	0.3	
		I _{OL} = 12 mA	2.3 to <2.7	-	-	0.4	-	0.4	
			2.7 to 3.6	-	-	0.4	-	0.4	
		I _{OL} = 18 mA	2.3 to <2.7	-	-	0.6	-	0.6	
			2.7 to 3.6	-	-	0.4	-	0.4	
		I _{OL} = 24 mA	2.7 to 3.6	-	-	0.55	-	0.55	
I _{IN}	Input Leakage Current	V _{IN} = 0 V to 3.6 V	0.9 to 3.6	-	-	±0.1	-	±0.5	μΑ
l _{OFF}	Power Off Leakage Current	V _{IN} = 0 V to 3.6 V or V _{OUT} = 0 V to 3.6 V	0	_	-	0.5	-	0.5	μΑ
I _{CC}	Quiescent Supply Current	V _{IN} = V _{CC} or GND	0.9 to 3.6	-	_	0.9	-	0.9	μΑ

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

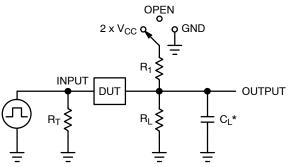
AC ELECTRICAL CHARACTERISTICS

				T _A = 25°C		$T_A = 25^{\circ}C$ $T_A = -40^{\circ}C \text{ to } +85^{\circ}C$			
Symbol	Parameter	Condition	V _{CC} (V)	Min	Тур	Max	Min	Max	Unit
t _{PLH} ,	Propagation Delay,	$R_L = 1 \text{ M}\Omega$, $C_L = 15 \text{ pF}$	0.9	-	17.4	_	-	-	ns
t _{PHL}	A to Y (Figures 3 and 4)	$R_L = 2 \text{ k}\Omega$, $C_L = 15 \text{ pF}$	1.1 to 1.3	_	5.3	12.5	-	14.9	
			1.4 to 1.6	-	2.9	5.4	-	6.0	
		$R_L = 500 \ \Omega, \ C_L = 30 \ pF$	1.65 to 1.95	-	2.5	4.6	-	5.2	
			2.3 to 2.7	-	1.9	3.6	-	3.8	
			2.7 to 3.6	-	1.6	3.0	-	3.3	

CAPACITIVE CHARACTERISTICS

Symbol	Parameter	Test Condition	Typical (T _A = 25°C)	Unit
C _{IN}	Input Capacitance	V _{CC} = 0 V	2.0	pF
C _{OUT}	Output Capacitance	V _{CC} = 0 V	4.5	pF
C _{PD}	Power Dissipation Capacitance (Note 5)	$f = 10 \text{ MHz}$, $V_{CC} = 0.9 \text{ to } 3.6 \text{ V}$, $V_{IN} = 0 \text{ V or } V_{CC}$	10.0	pF

^{5.} C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation $I_{CC(OPR)} = C_{PD} \bullet V_{CC} \bullet f_{in} + I_{CC}$. C_{PD} is used to determine the no–load dynamic power consumption: $P_D = C_{PD} \bullet V_{CC}^2 \bullet f_{in} + I_{CC} \bullet V_{CC}$.



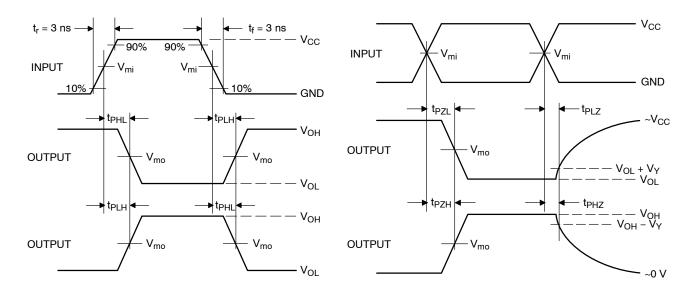
Test	Switch Position
t _{PLH} / t _{PHL}	Open
t _{PLZ} / t _{PZL}	2 x V _{CC}
t _{PHZ} / t _{PZH}	GND

 C_L includes probe and jig capacitance

 R_{T} is Z_{OUT} of pulse generator (typically 50 $\Omega)$

f = 1 MHz

Figure 3. Test Circuit



V _{CC} , V	V_{mi}, V	V_{mo}, V	V _Y , V
0.9	V _{CC} / 2	V _{CC} / 2	0.1
1.1 to 1.3	V _{CC} /2	V _{CC} /2	0.1
1.4 to 1.6	V _{CC} / 2	V _{CC} /2	0.1
1.65 to 1.95	V _{CC} / 2	V _{CC} /2	0.15
2.3 to 2.7	V _{CC} / 2	V _{CC} /2	0.15
3.0 to 3.6	1.5	1.5	0.3

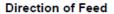
Figure 4. Switching Waveforms

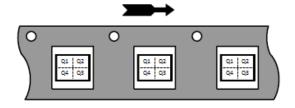
ORDERING INFORMATION

Device	Package	Marking	Pin 1 Orientation (See below)	Shipping [†]
NC7WV04P6X	SC-88	V04	Q4	3000 / Tape & Reel
NC7WV04L6X	MicroPak	ВА	Q4	5000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

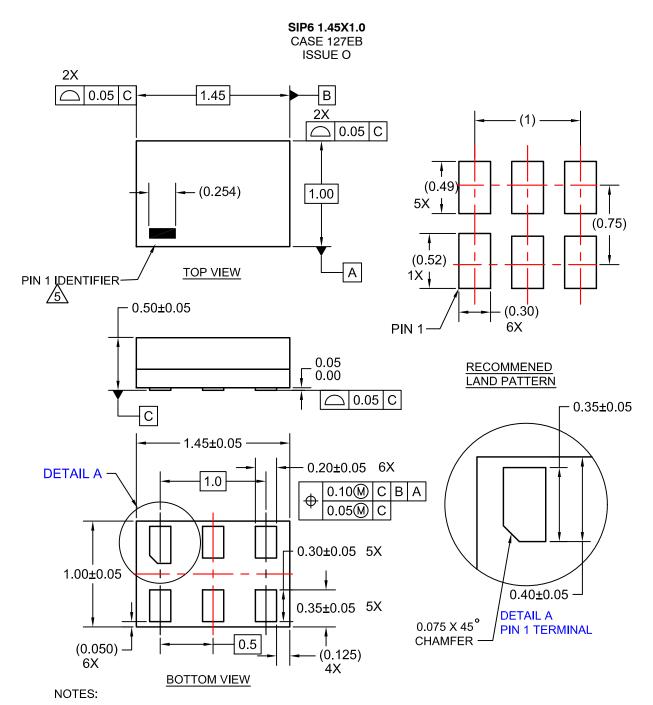
PIN 1 ORIENTATION IN TAPE AND REEL





MicroPak is trademark of Semiconductor Components Industries, LLC (SCILLC) or its subsidiaries in the United States and/or other countries.

PACKAGE DIMENSIONS



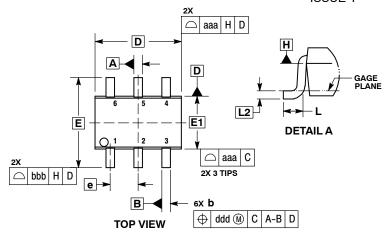
- 1, CONFORMS TO JEDEC STANDARD MO-252 VARIATION UAAD
- 2. DIMENSIONS ARE IN MILLIMETERS
- 3. DRAWING CONFORMS TO ASME Y14.5M-2009
- 4\PIN ONE IDENTIFIER IS 2X LENGTH OF ANY

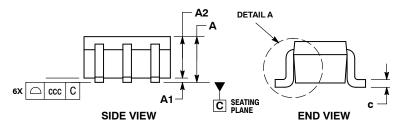
OTHER LINE IN THE MARK CODE LAYOUT.

PACKAGE DIMENSIONS

SC-88/SC70-6/SOT-363

CASE 419B-02 **ISSUE Y**



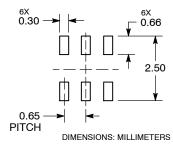


NOTES

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- CONTROLLING DIMENSION: MILLIMETERS.
 DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH,
 PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRU-SIONS, OR GATE BURRS SHALL NOT EXCEED 0.20 PER END.
- SIONS, OR GATE BORNS SHALL NOT EACEED 0.20 FER END.
 DIMENSIONS D AND E1 AT THE OUTERMOST EXTREMES OF
 THE PLASTIC BODY AND DATUM H.
 DATUMS A AND B ARE DETERMINED AT DATUM H.
 DIMENSIONS B AND 6 APPLY TO THE FLAT SECTION OF THE
- LEAD BETWEEN 0.08 AND 0.15 FROM THE TIP.
 DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION.
- ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 TOTAL IN EXCESS OF DIMENSION b AT MAXIMUM MATERIAL CONDI-TION. THE DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OF THE FOOT.

	MIL	LIMETE	ERS		INCHES	3
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α			1.10			0.043
A1	0.00		0.10	0.000		0.004
A2	0.70	0.90	1.00	0.027	0.035	0.039
b	0.15	0.20	0.25	0.006	0.008	0.010
С	0.08	0.15	0.22	0.003	0.006	0.009
D	1.80	2.00	2.20	0.070	0.078	0.086
E	2.00	2.10	2.20	0.078	0.082	0.086
E1	1.15	1.25	1.35	0.045	0.049	0.053
е		0.65 BS	С	0.026 BSC		
L	0.26	0.36	0.46	0.010	0.014	0.018
L2	0.15 BSC			(0.006 BS	SC
aaa	0.15				0.006	
bbb	0.30				0.012	
ccc	0.10			0.004		
ddd	0.10				0.004	

RECOMMENDED **SOLDERING FOOTPRINT***



*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

onsemi. On Semi, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries. LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries. onsemi owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of onsemi's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. onsemi reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and onsemi makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does **onsemi** assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using **onsemi** products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by **onsemi**. "Typical" parameters which may be provided in **onsemi** data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. **onsemi** does not convey any license under any of its intellectual property rights nor the rights of others. **onsemi** products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use **onsemi** products for any such unintended or unauthorized application, Buyer shall indemnify and hold **onsemi** and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that **onsemi** was negligent regarding the design or manufacture of the part. **onsemi** is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

ADDITIONAL INFORMATION

TECHNICAL PUBLICATIONS:

Technical Library: www.onsemi.com/design/resources/technical-documentation

onsemi Website: www.onsemi.com

ONLINE SUPPORT: www.onsemi.com/support

For additional information, please contact your local Sales Representative at www.onsemi.com/support/sale